

1N5614 S2M 1N5616 S4M 1N5618 S6M 1N5620 S8M 1N5622 S0M

January 7, 1998

CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	1N5614 1N5616 1N5618 1N5620 1N5622 S2M S4M S6M S8M S0M	Unit
Average forward current (sine wave) - max. pcb mounted; T _A = 55°C - max. L = 3/8"; T _L = 55°C	I _{F(AV)}	1.0	A A
I^2 t for fusing (t = 8.3mS) max.	I ² t	5.0 ────	A^2S
Forward voltage drop max. @ $I_F = 1.0A$, $T_j = 25^{\circ}C$	V_{F}	← 1.1 − →	V
Reverse current max. @ V_{RWM} , $T_j = 25^{\circ}C$ @ V_{RWM} , $T_j = 100^{\circ}C$	I _R I _R	0.5	μΑ μΑ
Reverse recovery time max. 0.5A I _F to 1.0A I _R . Recovers to 0.25A I _{RR} .	t _{rr}	← 2.0 ←	μS
Junction capacitance typ. @ $V_R = 5V$, $f = 1MHz$	Cj	23	ρF
Thermal resistance - junction to lead Lead length = 0.375" Lead length = 0"	R _{0JL} R _{0JL}		°C/W °C/W
Thermal resistance - junction to amb. on 0.06" thick pcb. 1 oz. copper.	R _{0JA}	← 95 − − − − −	°C/W

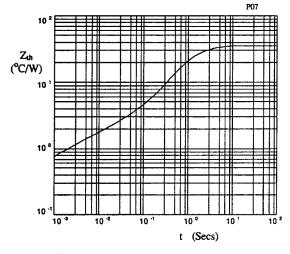


Fig 1. Transient thermal impedance characteristic.

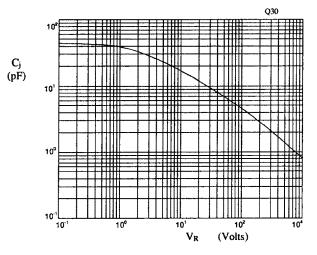


Fig 2. Typical junction capacitance as a function of reverse voltage.



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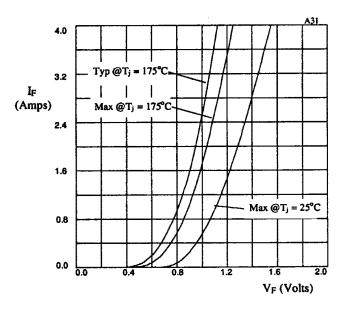


Fig 3. Forward voltage drop as a function of forward current.

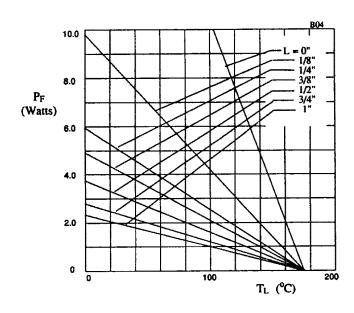


Fig 4. Maximum power versus lead temperature.

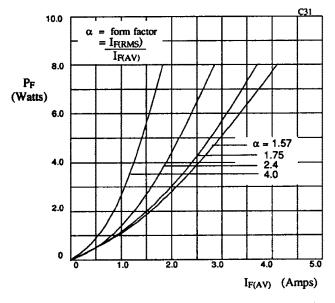


Fig 5. Forward power dissipation as a function of forward current, for sinusoidal operation.

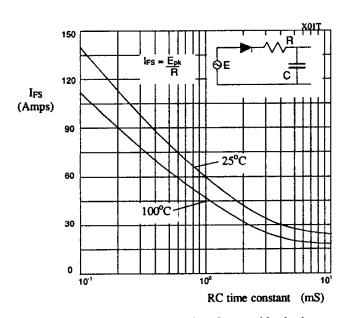


Fig 6. Maximum ratings for capacitive loads.

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